



**JOCDA4AB-D8P/S Series**

Rev.A.1.0

**DESCRIPTION:**

The products are gate driver opto-couplers in a plastic DIP8 package with differerferer

**ABSOLUTE MAXIMUM RATINGS** (Temperature=25°C)

Parameter		Symbol	Value	Unit
LED	Forward Current	$I_F$	50	mA
	Peak Forward Current	$I_{FP}$	1	A
	Reverse Voltage	$V_R$	6	V
	Power Dissipation	$P_D$	100	mW
Detector	Output Voltage	$V_O$	35	V
	Supply Voltage	$V_{CC}$	35	V
	Power Dissipation	$P_C$	400	mW
Isolation Voltage		$V_{iso}$	5000	Vrms
Operating Temperature		$T_{opr}$	-40~110	
Junction Temperature		$T_j$	125	
Storage Temperature		$T_{stg}$	-55~125	
Total Power Dissipation		$P_{tot}$	500	mW
Soldering Temperature		$T_{sol}$	260	

NOTE1 100μs pulse, 100Hz frequency

NOTE2 AC for 1minute, R.H.=40~60%

**ELECTRICAL CHARACTERISTICS** (Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	$V_F$	$I_F=10mA$	-	1.35	1.6	V
	Reverse Current	$I_R$	$V_R=6V$	-	-	1	μA
	Terminal Capacitance	$C_t$	$V=0, f=1MHz$	-	60	-	pF
Output	Peak High-level Output Current	$I_{OPH}$	$V_O=V_{CC}-4V,$ Pulse width 50μs	-1	-	-	A
			$V_O=V_{CC}-10V,$ Pulse width 10μs	-3	-	-	A
	Peak Low-level Output Current	$I_{OPL}$	$V_O=V_{EE}+2.5V,$ Pulse width 50μs	1	-	-	A
			$V_O=V_{EE}+10V,$ Pulse width 10μs	3	-	-	A
	High Level Supply Current	$I_{CCH}$	$I_F=10mA$ $R_g=10 \Omega,$ $C_g=25nF$	-	1.9	3	mA
	Low Level Supply Current	$I_{CCL}$	$V_F=0V,$ $R_g=10 \Omega,$ $C_g=25nF$	-	1.9	3	mA

High Level Output Voltage	$V_{OH}$	$I_F=5mA,$ $V_{CC}=10V,$ $I_O=-100mA$	6	8.4	-	V
Low Level Output Voltage	$V_{OL}$	$V_F=0.8V,$ $V_{CC}=10V,$ $I_O=100mA$	-	0.3	1	V
Threshold Input Current	$I_{FLH}$	$V_{CC}=15V,$ $V_O 1V$	-	1.5	4	mA
Threshold Input Voltage	$V_{FHL}$	$V_{CC}=15V,$ $V_O 1V$	0.8	-	-	V
Supply Voltage	$V_{CC}$	-	15	-	30	V
UVLO Threshold	VUVLO+	$V_O 5V,$ $I_F=10mA$	12.1	12.8	13.5	V
	VUVLO-	$V_O 5V,$ $I_F=10mA$	11.1	11.8	12.4	V

**SWITCHING SPECIFICATION**

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Propagation Delay Time to High Output Level	$t_{PLH}$	$R_g=47 \Omega,$ $C_g=3nF,$ $I_F=0 \text{ mA},$ $V_{CC}=30V$	30	-		

Common Mode Transient Immunity at Low Level Output	CML	I <sub>F</sub> =0mA V <sub>CC</sub> =30V, T <sub>a</sub> =25 , V <sub>O(max)</sub> =1V V <sub>CM</sub> =1000Vpp	±35	-	-	kV/μs
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All Typical values at T<sub>a</sub>=25

**Note1:** Input signal (f=25kHz,duty=50%, tr=tf=5ns or less). C<sub>L</sub> is less than 15 pF which includes probe and stray wiring capacitance.

**Note2** CM<sub>H</sub> is the maximum rate of fall of the common mode voltage that can be sustained with the output voltage in the logic high state (V<sub>O</sub> = 26V).

**Note3** CML is the maximum rate of rise of the common mode voltage that can be sustained with the output voltage in the logic low state (V<sub>O</sub> = 1V).

### Recommended Operating Conditions

Characteristics	Symbol	Min.	Typ.	Max.	Unit
Input On-state Current	I <sub>F(ON)</sub>	6.5	-	10	mA
Input Off-state Voltage	V <sub>F(OFF)</sub>	0	-	0.8	V
Supply Voltage	V <sub>CC</sub>	15	-	30	V
Operating Frequency	f	-	-	25	KHz

**Note1:** The recommended operating conditions are given as a design guide necessary to obtain the intended performance of the device. Each parameter is an independent value. When creating a system design using this device, the electrical characteristics specified in this datasheet should also be considered.

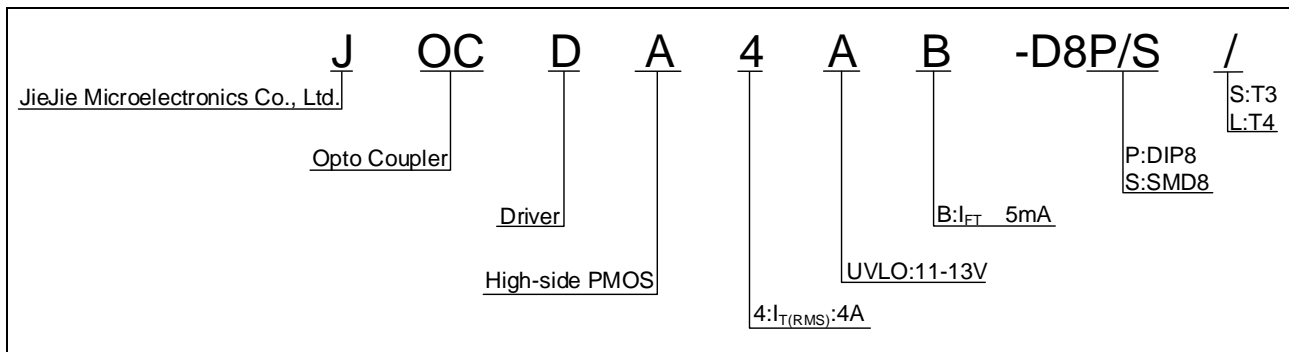
**Note2** A ceramic capacitor(0.1μF) should be connected between pin 6 (V<sub>CC</sub>) and pin 4 (GND) to stabilize the operation of a high gain linear amplifier. Otherwise, this photocoupler may not switch properly. The bypass capacitor should be placed within 1 cm of each pin.

**Note3** The rise and fall times of the input on current should be less than 0.5 μs.

**Note4:** If the rising slope of the supply voltage (V<sub>CC</sub>) for the detector is steep, stable operation of the internal circuits cannot be guaranteed. Be sure to set 3V/μs or less for a rising slope of the V<sub>CC</sub>.

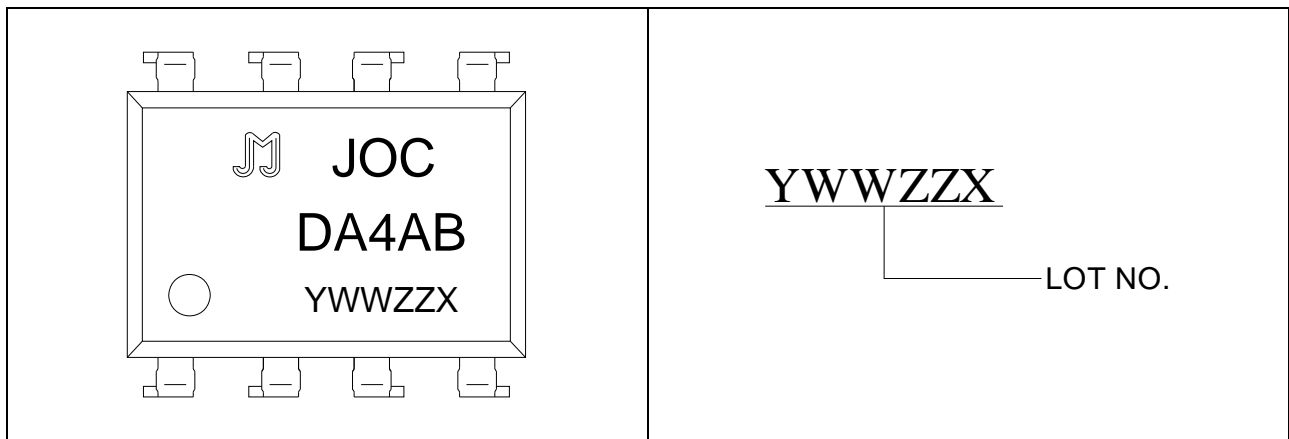
**Note5** Denotes the operating range, not the recommended operating condition.

ORDERING INFORMATION



Packing Quantity	
Option	Quantity
DIP	50 Units/Tube
SMD	1200 Units/Reel

MARKING



Characteristics Curves

FIG.1: Forward Current vs. Forward Voltage

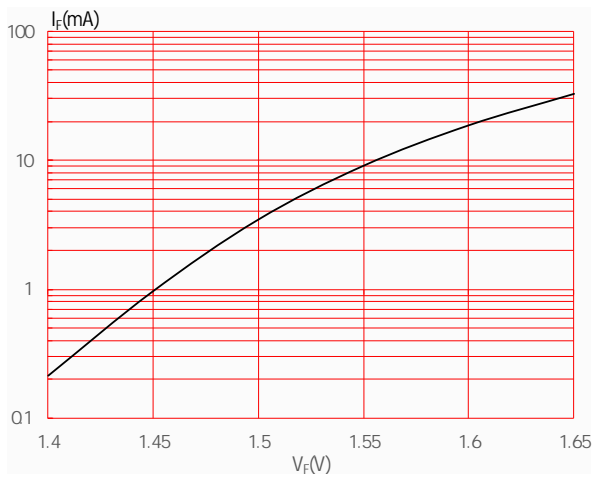


FIG.2: Max. Allowable LED Forward Current vs. Ambient Temperature

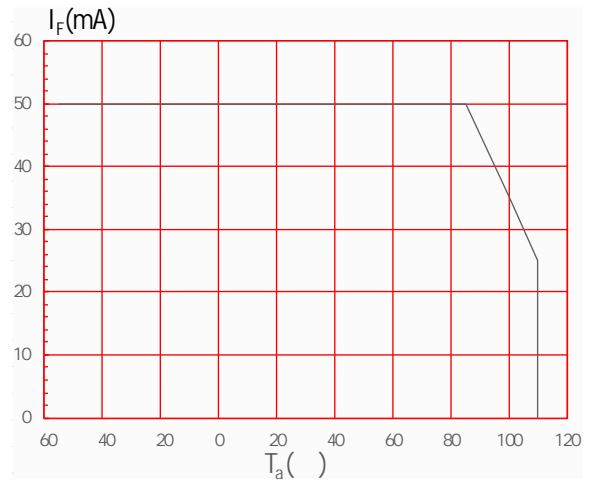


FIG.3: Collector Power Dissipation vs. Ambient Temperature

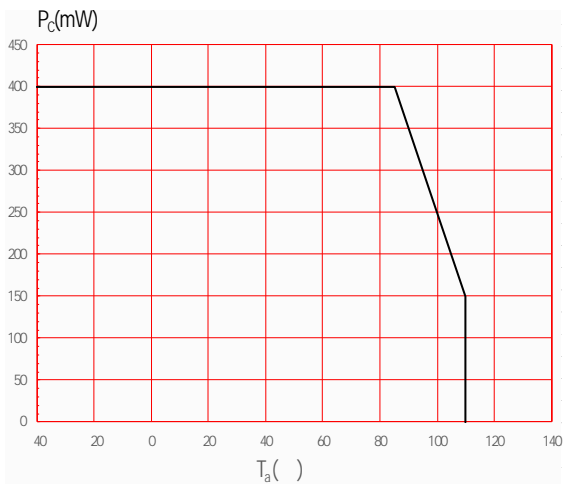


FIG.4: Threshold Input Current vs. Ambient Temperature

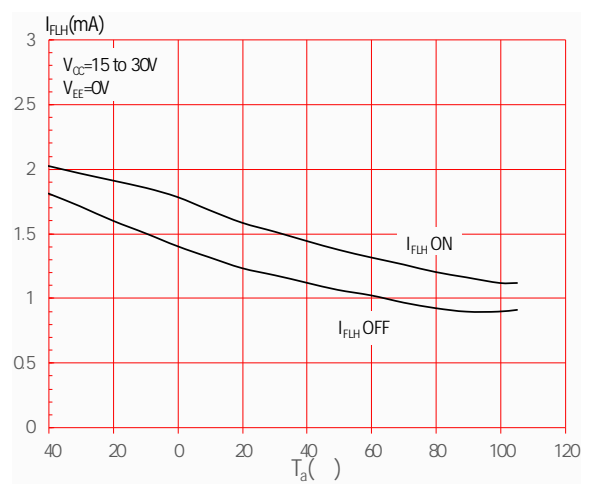


FIG.5: Low-level Supply Current vs. Ambient Temperature

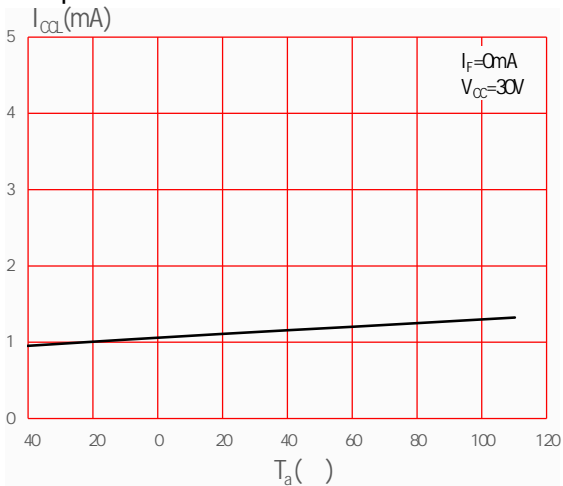
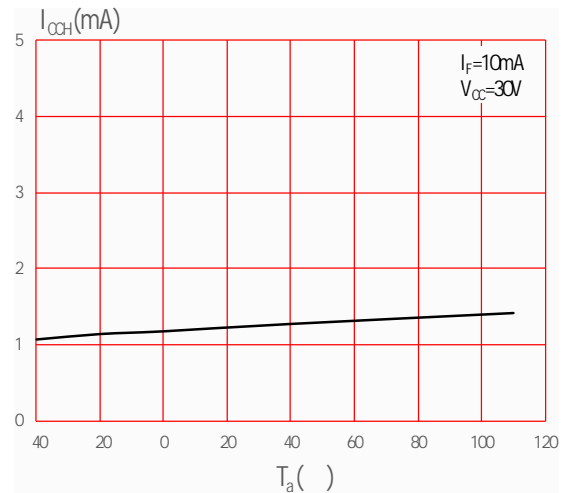
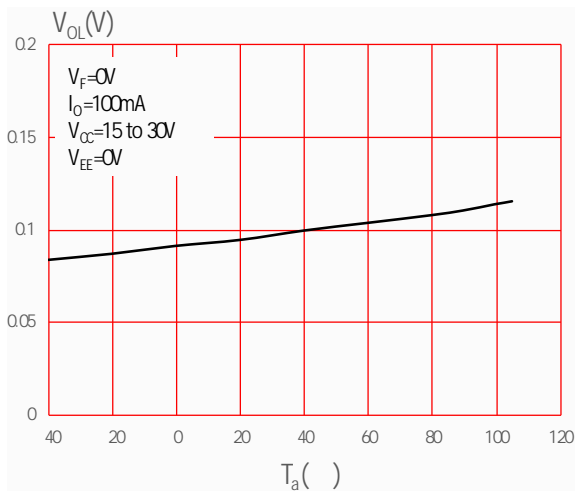


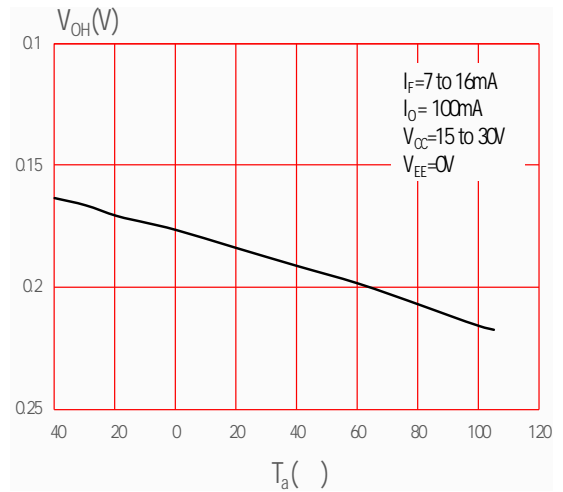
FIG.6: High-level Supply Current vs. Ambient Temperature



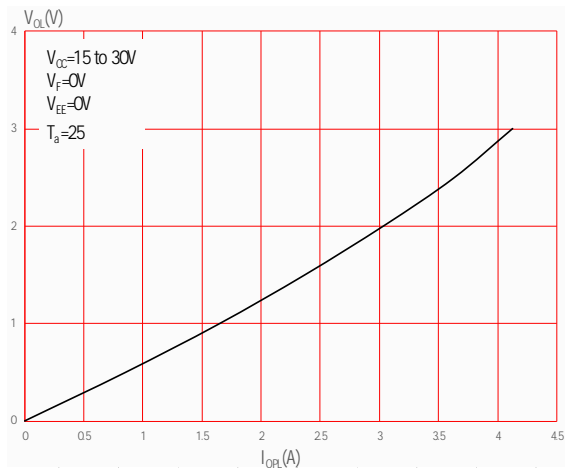
**FIG.7:** Low-level Output Voltage vs. Ambient Temperature



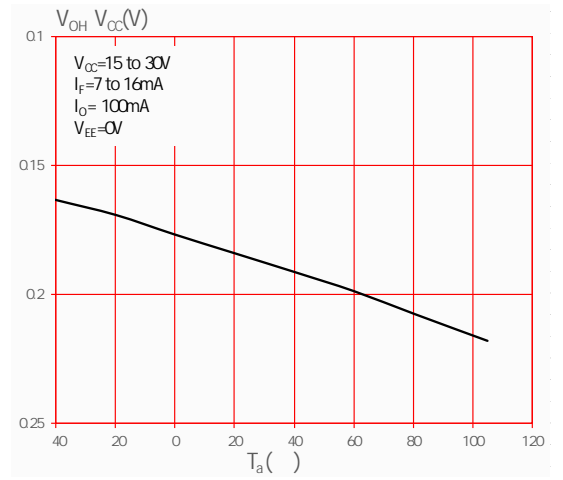
**FIG.8:** High-level Output Voltage vs. Ambient Temperature



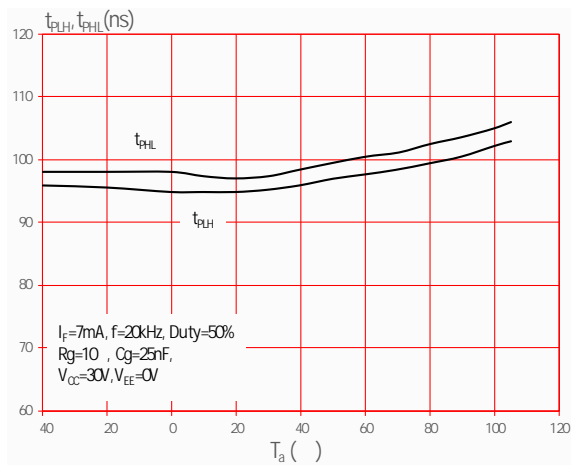
**FIG.9:** Peak Low-level Output Current vs. Low-level Output Voltage



**FIG.10:** High-level Output Voltage Drop vs. Ambient Temperature



**FIG.11:** Propagation Delay Time vs. Ambient Temperature

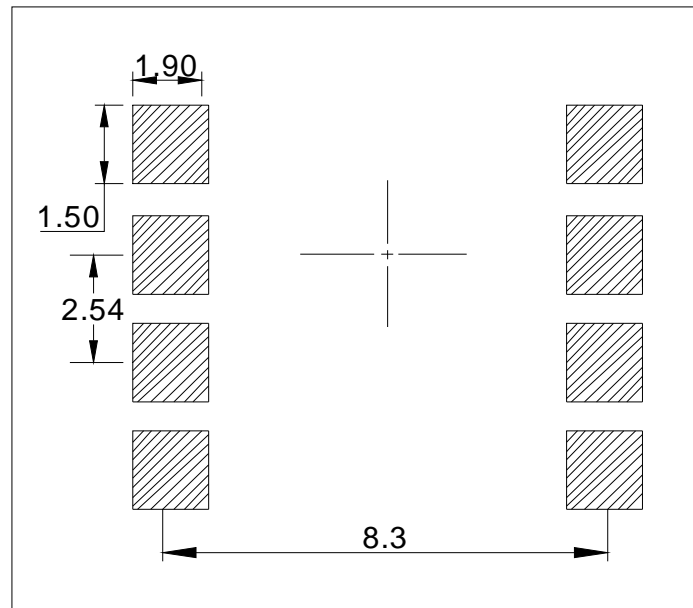


**FIG.12:** Propagation Delay Time vs. Forward Current

**JOCDA4AB**

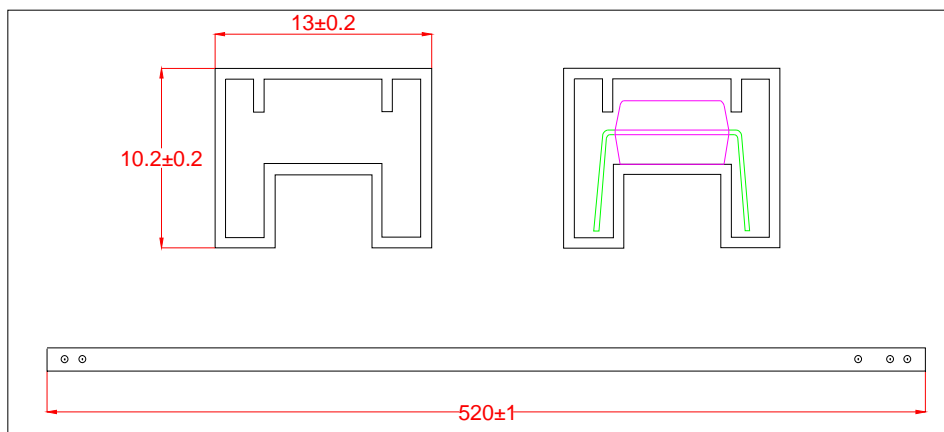
**JOCDA4AB**

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)



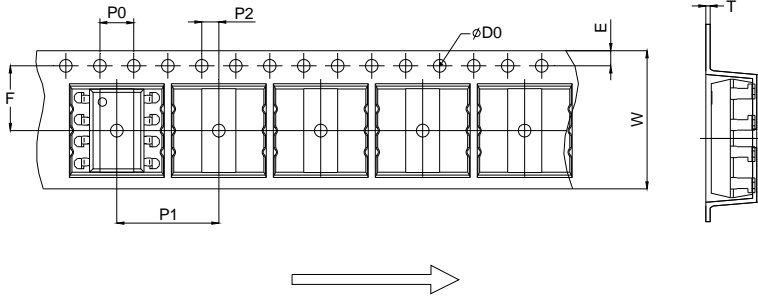
TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Standard DIP



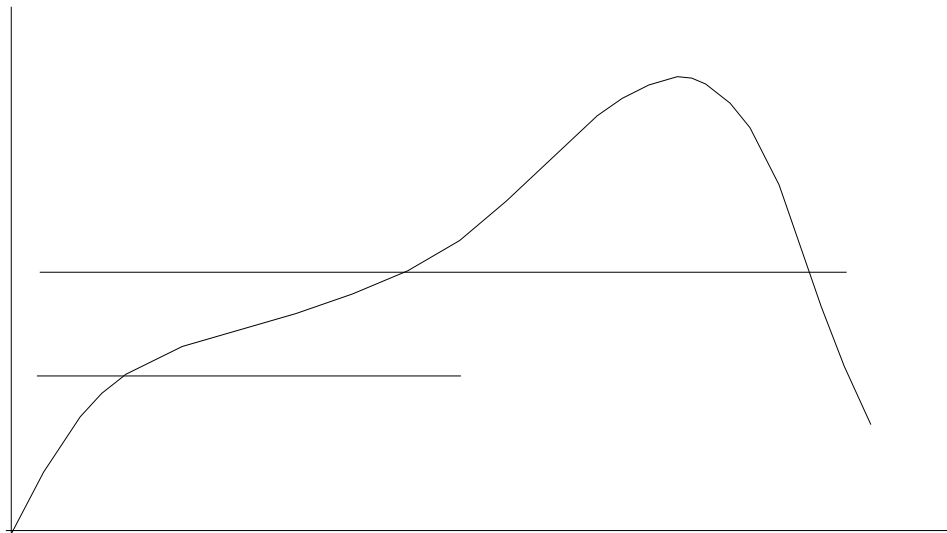
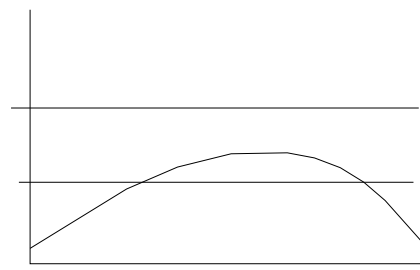
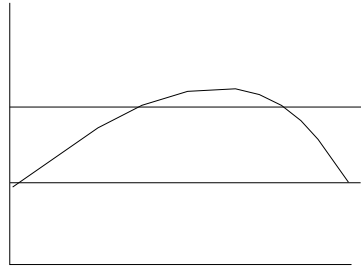
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option S/L

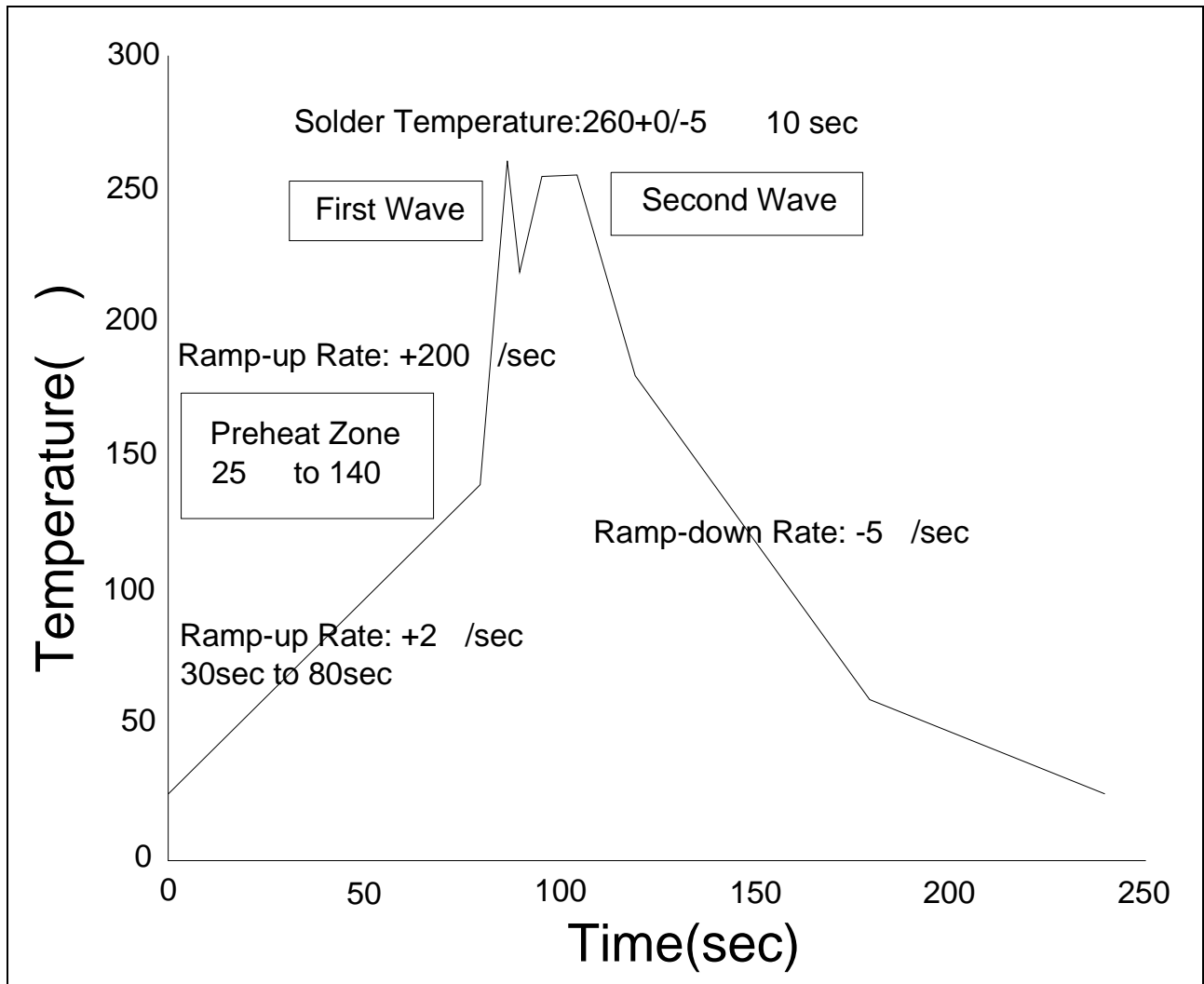


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.90	16.00	16.20	0.626	0.630	0.638

REFLOW INFORMATION



WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON

Soldering Temperature	360 5
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at e